External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.51899	100.0	1.2
			Subtotal	0.51899	100	1.2
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.5914	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
			Subtotal	1.59156	100	3.68
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01201	0.03	0.02778
	Copper alloy	Iron (Fe)	7439-89-6	0.04005	0.1	0.0926
	Copper alloy	Copper (Cu)	7440-50-8	39.88824	99.6	92.2296
	Pure metal layer	Silver (Ag)	7440-22-4	0.10813	0.27	0.25002
			Subtotal	40.04843	100	92.6
Adhesive	Polymer	Paraffin wax	8002-74-2	0.19808	20.0	0.458
	Polymer	Epoxy resin system		0.07923	8.0	0.1832
	Filler	Silver (Ag)	7440-22-4	0.71309	72.0	1.6488
			Subtotal	0.9904	100	2.29
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.42105	2.5	3.28575
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.26315	7.5	9.85725
	Filler	Silica -amorphous-	7631-86-9	21.03153	37.0	48.6291
	Pigment	Carbon black	1333-86-4	0.28421	0.5	0.65715
	Polymer	Epoxy resin system		8.5263	15.0	19.7145
	Filler	Silicon Dioxide (SiO2)	14808-60-7	21.03153	37.0	48.6291
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.28421	0.5	0.65715
			Subtotal	56.84198	100	131.43
Wire	Pure metal	Copper (Cu)	7440-50-8	0.00865	100.0	0.02
			Subtotal	0.00865	100	0.02
			Total	100.00001	100	231.22

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